

Company Overview

MMIC, RFIC and microwave/mmWave module design specialists

PRFI Ltd. is a UK-based design house specialising in the design and development of RFICs and MMICs, and microwave/mmWave modules. Projects range from feasibility studies to the design and development of microwave ICs, components and sub-systems. Our offices and labs are located near Cambridge, in the UK.





Technology

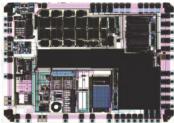
Our skills cover RF, microwave and mmWave components and subsystem development including: custom IC design (GaAs, GaN and Si), high frequency SMT based PCBs, chip and wire assemblies, MCMs, LTCC, thin-film and custom IC package design. We have designed over 100 ICs at frequencies ranging from baseband to 100GHz and are a third party design house for Cree (Wolfspeed), GCS, Qorvo and WIN.

Clients

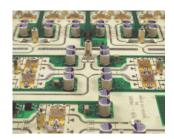
Our clients range from start-ups to major multi-nationals. Companies that have used PRFI's services include Aeroflex, Analog Devices, BAE Systems, Huawei, Inmarsat, National Semiconductor, QinetiQ, Qorvo, Samsung, Sony Semiconductor, Selex, TDK and Thales.

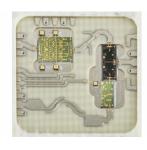
Project Examples





SiC





GaAs/GaN MMIC



Microwave/mmWave

the design and supply of an 8 to

18GHz, fast switching, low noise

synthesiser; a fast switching (<10ns) 200W X-band solid-

state PA for a marine radar

application, high power amplifiers

and signal sources for space

applications, and a dual-channel 2

to I8GHz receiver for ESM.



PRFI's design services are used Our experience includes frontend ICs for mmWave 5G, by industry leading IC vendors. broadband MMICs for ESM. National Semiconductor used receiver, transmitter and PA ICs our design services to help for point to point microwave create an innovative world class links and GaN PAs for both transceiver design that has sold commercial and defence appin excess of I billion units. PRFI lications. We use industry-leading has also worked on the design CAD software for our designs and packaging of mmWave ICs and have our own in-house test for 5G applications using bulk lab for evaluation of both bare-CMOS. die (RFOW) and packaged

We have extensive experience of SMT packaging to mmWave frequencies. This includes the use of standard plastic overmould packages with custom designed lead-frames, the use of COTS ceramic and open-moulded plastic packages and the design of full custom laminate and ceramic packages. We have also developed SMT compatible multi-chip modules (MCMs) and Antennain-Package (AiP) solutions.

MMICs.